

What is claimed is:

1. A paddle type developing apparatus of photoresist in which a developing solution from a nozzle is supplied to an object to be treated, which is held by a chuck device, and the developing solution on the object to be treated is thrown off by rotating a spinner constituting the chuck device after a lapse of a prescribed time, wherein the paddle type developing apparatus comprises a nozzle which mixes a developing solution and air and spouts a developing solution in mist form and at least part of a developing solution pipe leading to this nozzle is disposed within a circulation path of temperature regulating water.
2. The developing apparatus according to claim 1, wherein part of the circulation path of temperature regulating water is formed in said chuck device and the temperature of said chuck is adjusted in part of this circulation path.
3. The developing apparatus according to claim 1, wherein at least part of an air pipe which supplies air to be mixed with said developing solution is disposed within the circulation path of temperature regulating water.
4. The developing apparatus according to claim 1, wherein this developing apparatus comprises a blower which feeds the temperature-regulated air into the developing apparatus and a preheating device which beforehand heats the object to be treated before the transfer of this object into the developing apparatus.
5. The developing apparatus according to claim 1, wherein a bottom surface of a cup is provided with a projecting body which prevents the developing solution from flowing behind a rear surface of the wafer.

6. The developing apparatus according to claim 1, wherein the spinner is provided with convex projections which generate air currents in a radial direction on a rear surface of the substrate, which is the object to be treated, by cutting air by rotation.
7. The developing apparatus according to claim 1, wherein said nozzle which spouts a developing solution in mist form is disposed within an antiscattering cone.
8. A developing method which uses the developing apparatus according to any one of claims 1 to 7, wherein a regulated temperature of said developing solution, a regulated temperature of said chuck device, a regulated temperature of said air to be mixed with the developing solution and/or a regulated temperature of said air to be fed into the developing apparatus is not less than 30°C but less than 60°C.
9. A developing method which uses the developing apparatus according to any one of claims 1 to 7, wherein this developing method is applied to the development treatment of a thick film photoresist of not less than 10 μm .